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- Amplifier board assembly and testing
- Motherboard Design
- Motherboard schematic
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Challenges

 Understand the function of the STURM2 device as whole

• Learn the PADS schematic and layout

• Learn component selection

Manage BOM

Overview of the STURM2 project

 The device is developed as part of the KEKB particle accelerator upgrade to Super-KEKB

• The device is used to monitor electron beam bunches profile



http://accl.kek.jp/eng/acclmap_e.html

Overview of the STURM₂ project

 The Super-KEKB has electron bunch sizes less than one nanometer, which requires a new device to measure the beam profile

 More accurate measurements can be done by using X – ray detector

 When electron beam is bended, it emits an X – ray beam



http://www.phys.hawaii.edu/~idlab/taskAndSchedule/STURM/STURM.html

Overview of the STURM2 project By measuring the profile of this X – ray beam, it is possible to calculate the beam size

 The X – ray beam is focused to fermionics sensor on the motherboard

• The KEKB ring is 3 kilometers long, and the electron beam travels nearly the speed of light

Very high speed measurement needed

Overview of the STURM2 project
The X –rays hitting the sensor releases electron-hole pairs

• 3.6 KeV releases 1000 electron-hole pairs

• With a sensor low-high response time of 0.25 nanoseconds, 3.6 KeV produces 0.7 microamp current

 The analog transfer line is fitted to 50Ω, so the output voltage from the sensor is 35 microvolts

Overview of the STURM2 project

• At least 10 mV output is needed in order to get the signal in to reasonable signal to noise ratio

• With 35 μV input signal, the total gain needed is 60 dB

 This requires three stages of amplifiers, each with 20 dB amplification

Amplifier board assembly

 The first amplifier boards were assembled in the lab by hand

The assembly was relatively easy, except



Amplifier board assembly

 The problem was to align the small RF connectors in the bottom of the board



Amplifier board testing

 To test the amplifier board, a carrier board was also manufactured

• Same problem with the RF connectors

 The amplifier board revision C reached the desired amplification



Motherboard desing

• The motherboard houses

192 amplifier cards
8 ASIC cards
Fermionics sensor
SCROD

Fermionics sensor bonding
Stability
cooling

Motherboard schematic

 Several new components had to be made

 The biggest job was naming and connecting all the nets

Time consuming





 One of the issues was to figure out the best bonding diagram for the sensor

 The first attempt was to make the bonding so that connecting pins in the bottom would be in numerical order

Didn't work at all



• Several other diagrams were tried, three in total







After a few discussions with the manufacturing company, a final diagram
 was made

 Additional wires were added to keep the bottom plane and the sensor pads at both ends at a constant voltage level



 This made routing more complex, since the pins on the CPG18020 socket were now on completely random order

 To make routing more easier, two layers were added to existing six



• Board dimensions 10,9 X 12 inches

• 8 electrical layers

7 different operating voltages from 1.2 volts to 5 volts
> 1,2 volts for SCROD
> 1,8 volts for SCROD
> 2,5 volts for SCROD and VPED
> 3,3 volts for SCROD
> 4 volts for amplifiers
> 5 volts for daughter cards
> Adjustable voltage for downbonds

• First thing to do is the component placing

 The board has over 400 components that need to be placed and routed by hand

Takes a long time



 To ease the routing, several different plane areas were created

VPED
Amp power
Downbonds
Two ground planes
Two power planes



 All the analog signals were routed by hand
 Transfer line impedance

 The digital signals were done by PADS auto router
 Crashes, bugs
 Needed to force the auto router by using keepouts





 The amplifiers draw most of the current, 31 milliamps each

• ≈ 6 amps in total

 Another power connector was added



 Fermionics sensor sits in the CPG18020 socket



 192 amplifiers, 96 on top and 96 on the bottom side



• 8 ASIC cards

Each card handles 8 channels



SCROD5 SMA connectors

Debugging (3) Real time clock (1) Downbonds (1)



Power connectors

Cooling areas on top and bottom



Function of the board

• The fermionics sensor produces the weak analog signal





Function of the board

Analog signal is amplified by 60 dB to 10 millivolts
Fixed low pass filter between amplifiers removes the spike found in testing



Function of the board Signal is then fed to the ASIC card, which holds the STURM2 ASIC chip



http://www.phys.hawaii.edu/~idlab/taskAndSchedule/STURM/STURM.html

STURM2 ASIC

 8 Channels, each has 4 storages, which each hold 8 samples

Adjustable sample delay

Makes an 12 bit analog / digital conversion

http://www.phys.hawaii.edu/~idlab/taskAndSchedule/STUR M/STURM.html



Function of the board

• The sampling speed of the device is 10 giga samples per second

• This produces a large amount of analog data

The STURM ASIC chip makes an analog / digital conversion

• This reduces the amount of data to be processed

Function of the board

 By changing the data signal to digital form allows longer connecting distances

 From the ASIC card the Signal is fed to the SCROD

 The SCROD connects to computer were the data can be analysed



Conclusion

• Learned a lot about schematic and layout design

Component selection

Problem solving

• Improved my English a lot

Questions / comments



Thanks for attending Kiitos osallistumisesta